

LNPTM STAT-LOYTM COMPOUND M3000C

M- CCS

DESCRIPTION

LNP STAT-LOY M3000C compound is based on unfilled Polypropylene (PP) resin containing proprietary fillers. Added features of this grade include: LNP Clean Compounding Technology, Permanently Anti-Static.

GENERAL INFORMATION	
Features	Antistatic, Low ionics/Outgassing/Liquid particle count, No PFAS intentionally added
Fillers	Unreinforced
Polymer Types	Polypropylene, Unspecified (PP, Unspecified)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, brk, Type I, 50 mm/min	18	MPa	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	689	%	ASTM D638
Tensile Modulus, 50 mm/min	760	MPa	ASTM D638
Flexural Strength, 1.3 mm/min, 50 mm span	24	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	860	MPa	ASTM D790
Tensile Stress, break, 50 mm/min	24	MPa	ISO 527
Tensile Strain, break, 50 mm/min	690	%	ISO 527
Tensile Modulus, 1 mm/min	1180	MPa	ISO 527
Flexural Strength, 2 mm/min	38	MPa	ISO 178
Flexural Modulus, 2 mm/min	1960	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, notched, 23°C	75	J/m	ASTM D256
Multiaxial Impact	25	J	ISO 6603
Instrumented Dart Impact Total Energy, 23°C	29	J	ASTM D3763
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	74	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	49	°C	ASTM D648
CTE, -30°C to 30°C, flow	1.28E-04	1/°C	ASTM D696
CTE, -30°C to 30°C, xflow	1.31E-04	1/°C	ASTM D696
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	75	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	49	°C	ISO 75/Af

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
PHYSICAL ⁽¹⁾			
Density	0.93	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.16	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1 – 2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1 – 2	%	ASTM D955
Density	0.93	g/cm ³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.16	%	ISO 62
ELECTRICAL ⁽¹⁾			
Surface Resistivity ⁽³⁾	1.E+10 – 1.E+12	Ω	ASTM D257
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	70 – 80	°C	
Drying Time	4	Hrs	
Melt Temperature	190 – 200	°C	
Front - Zone 3 Temperature	200 – 210	°C	
Middle - Zone 2 Temperature	195 – 205	°C	
Rear - Zone 1 Temperature	180 – 195	°C	
Mold Temperature	30 – 50	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Measurement meets requirements as specified in ASTM D4496.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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